

修订记录 / Revised record

版本	修订日期	有修订的页码	修订涉及的内容	拟制	审核
A	2020.08.04	All	基于 BRCS120N03ZB 规格书 , 参考 AON2420 规格书制作	庞隆基	陈逸晞
B	2020.09.15		RDSON 测试条件从原来的 10V/20A,4.5V/10A 改为 10V/8A,4.5V/6A	庞隆基	陈逸晞
C	2021-12-1	8	3000 一盘改为 4000 一盘	黄超	庞隆基

描述 / Descriptions

N 2*2B- 塑封封装 N 沟道 MOS 场效应管。

N-Channel Enhancement Mode Field Effect Transistor in a DFN 2*2B-6L Plastic Package.

特征 / Features

$V_{DS} (V) = 30V$

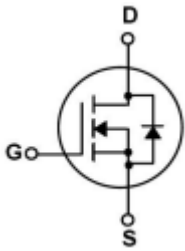
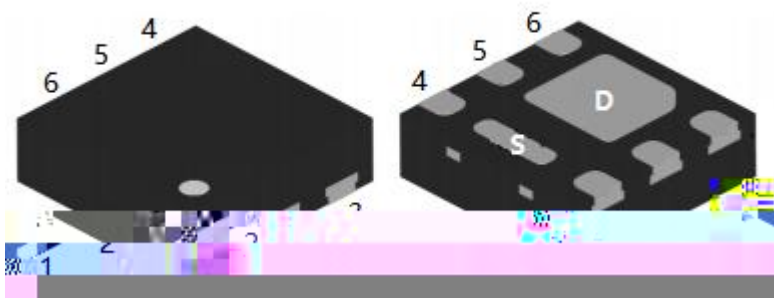
$I_D = 8 A (V_{GS} = \pm 20V)$

无卤产品。H Product.

用途 / Applications

用于低压电路如：汽车电路、 C/ C 转换、便携式产品的电源高效转换。

Suited for low voltage applications such as automotive, DC/DC Converters, and high efficiency switching for power management in portable and battery operated products.

内部等效电路 / Equivalent Circuit**引脚排列 / Pinning**

出脚	定义
Pin1	D
Pin2	D
Pin3	G
Pin4	S
Pin5	D
Pin6	D

放大及印章代码 / h_{FE} Classifications & Marking

见印章说明。See Marking Instructions.

极限参数 / Absolute Maximum Ratings(Ta=25°C)

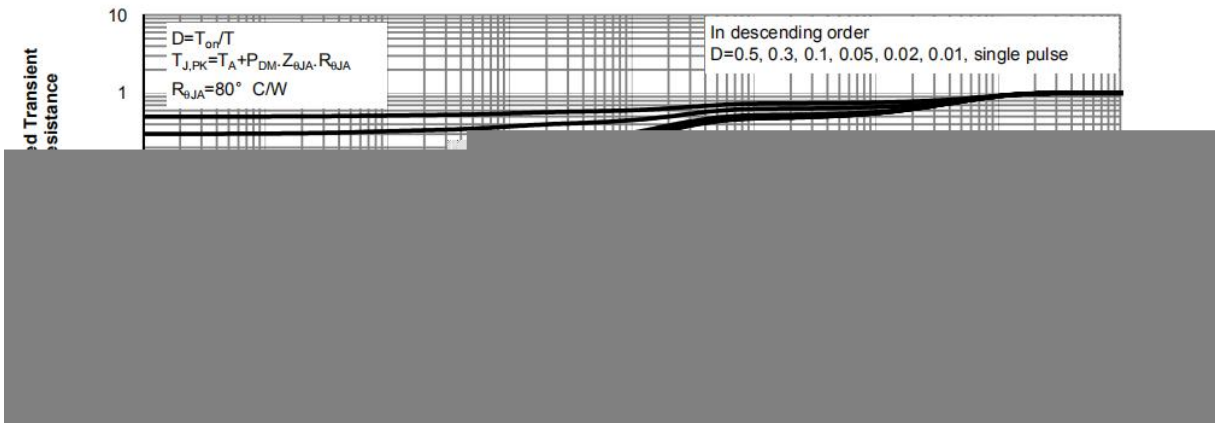
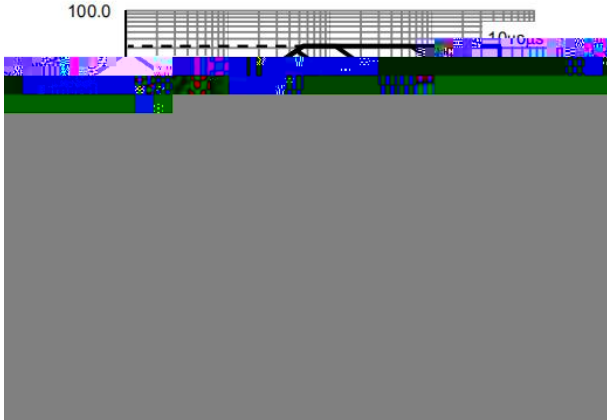
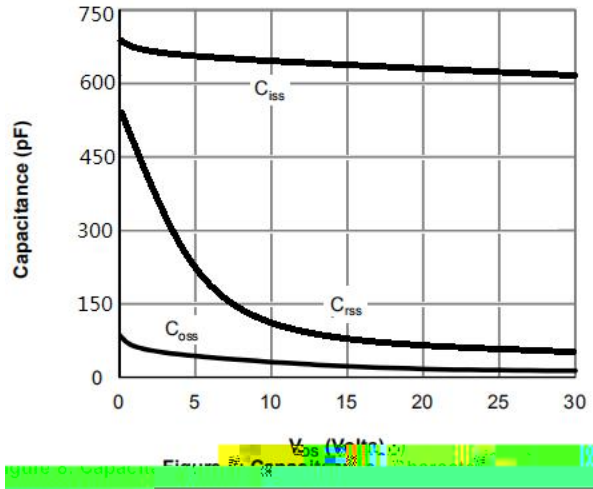
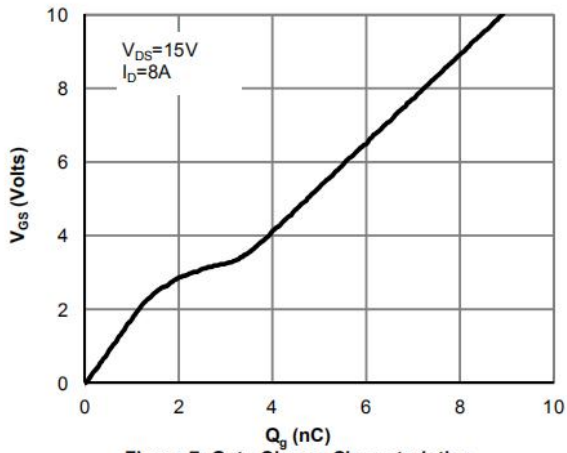
Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DSS}	30	V
Drain Current	$I_D(T_C=25^\circ\text{C})$	8	A
Gate-Source Voltage	V_{GS}	± 20	V
Avalanche Current	I_{AS}	12.9	A
Single Pulsed Avalanche Energy	E_{AS}	199	mJ
Power Dissipation	$P_D(T_C=25^\circ\text{C})$	2.8	W
Junction Temperature Range	T_j	150	$^\circ\text{C}$
Storage Temperature Range	T_{stg}	-55~150	$^\circ\text{C}$
Maximum Junction-to-Ambient	$t \leq 10\text{s}$	$R_{\theta JA}$	45
	Steady-State	$R_{\theta JA}$	80

电性能参数 / Electrical Characteristics(Ta=25°C)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0\text{V}$ $I_D=250\mu\text{A}$	30	34.7		V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=30\text{V}$ $V_{GS}=0\text{V}$			1.0	μA
		$V_{DS}=30\text{V}$ $T_J=150^\circ\text{C}$			50	
Gate-Body Leakage Current Forward	I_{GSS}	$V_{GS}=\pm 20\text{V}$ $V_{DS}=0\text{V}$			± 0.1	μA
Static Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS}=10\text{V}$ $I_D=8.0\text{A}$		12.8	14	m
		$V_{GS}=4.5\text{V}$ $I_D=6.0\text{A}$		18	20	m
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}$ $I_D=250\mu\text{A}$	1	1.8	2.5	V
Drain-Source Diode Forward Voltage	V_{SD}	$V_{GS}=0\text{V}$ $I_F=1.0\text{A}$		0.7	1.2	V
Signal Source Resistance	R_g	$F=1\text{MHz}$		1.67		
Input Capacitance	C_{iss}	$V_{DS}=25\text{V}$ $V_{GS}=0\text{V}$ $f=1.0\text{MHz}$		666		pF
Output Capacitance	C_{oss}			26		
Reverse Transfer Capacitance	C_{rss}			63		
Turn-On Delay Time	$t_{d(on)}$	$V_{DS}=15\text{V}$ $V_{GS}=10\text{V}$ $R_L=1.9$ $R_{GEN}=3.0$		4.8		ns
Turn-On Rise Time	t_r			3.3		
Turn-Off Delay Time	$t_{d(off)}$			18.5		
Turn-Off Fall Time	t_f			4.0		

Parameter	Symbol	Test Conditions	Min
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电参数曲线图 / Electrical Characteristic Curve

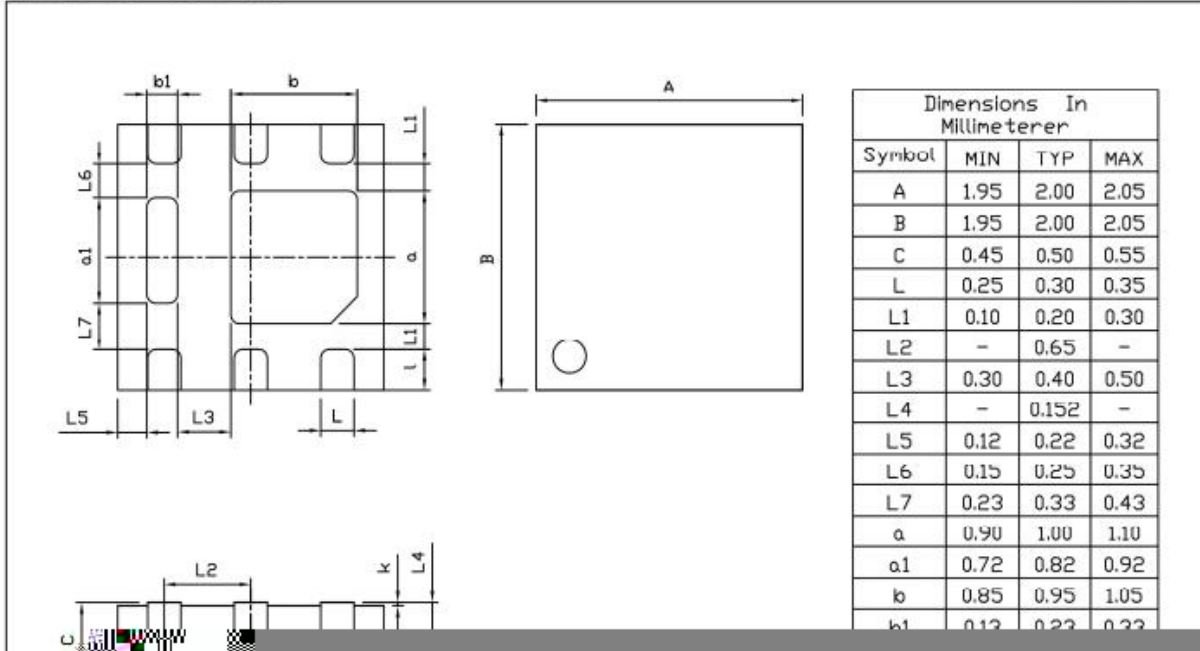


外形尺寸图 / Package Dimensions

DFN2×2B-6L-0.5 外形尺寸图

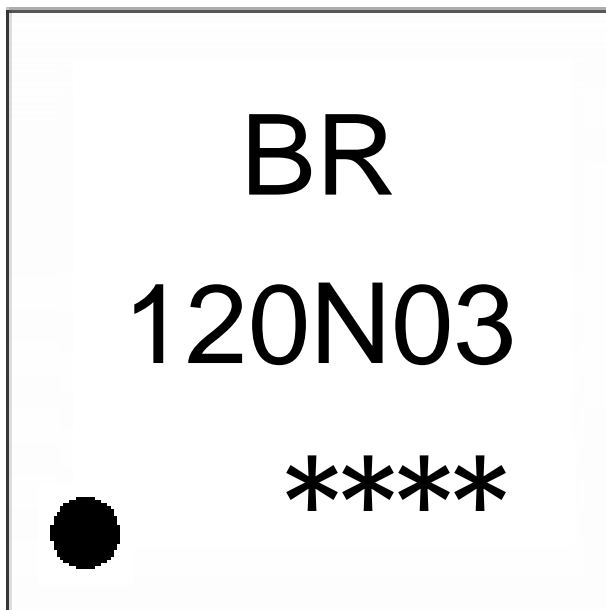
DFN2×2B-6L-0.5

Unit:mm





印章说明 / Marking Instructions



BR

120N03

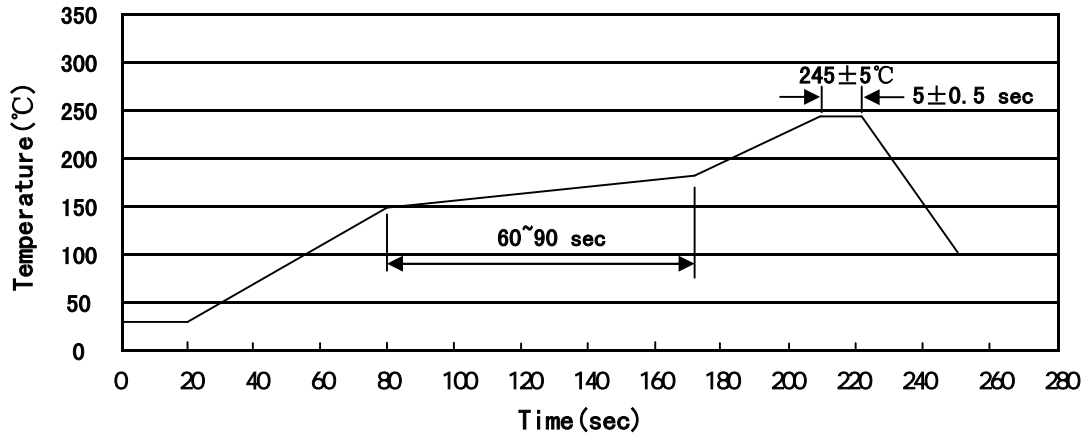
Note:

BR: Company Code.

120N03: Product Type

****: Lot No. Code, code change with Lot No.

回流焊温度曲线图(无铅) / Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

- | | | | | | |
|---|-------|-----|-----------|--------|---|
| 1 | 150 | 180 | 60 | 90sec; | 1. Preheating: 150~180°C, Time: 60~90sec. |
| 2 | 245±5 | | 5±0.5 | sec; | 2. Peak Temp.: 245±5°C, Duration: 5±0.5sec. |
| 3 | | 2 | 10°C/sec. | | 3. Cooling Speed: 2~10°C/sec. |

耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions

260±5°C 10±1 sec. Temp.: 260±5°C Time: 10±1 sec

包装规格 / Packaging SPEC.

/ REEL

Package Type	Units					Dimension (unit mm ³)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box	Outer Box
DFN 2*2B-6L	4,000	10	40,000	4	160,000	7" x8	210×205×205	445×230×435

使用说明 / Notices